

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
19 January 2006 (19.01.2006)

PCT

(10) International Publication Number
WO 2006/007141 A2

(51) International Patent Classification:

H01L 21/44 (2006.01) *H01L 23/52* (2006.01)
H01L 23/48 (2006.01) *H01L 21/50* (2006.01)
H01L 21/48 (2006.01) *H01L 29/40* (2006.01)

(21) International Application Number:

PCT/US2005/017702

(22) International Filing Date: 19 May 2005 (19.05.2005)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:

10/879,242 29 June 2004 (29.06.2004) US

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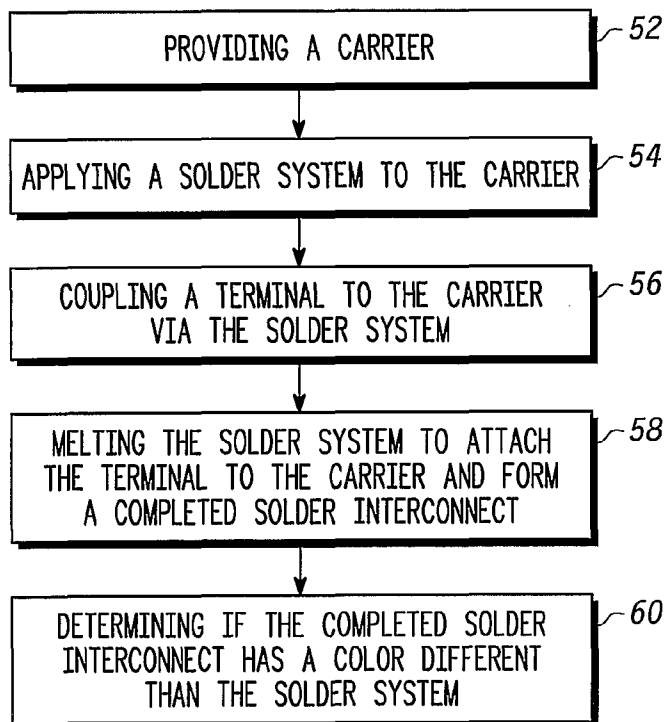
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(81) Designated States (*unless otherwise indicated, for every kind of national protection available*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

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(54) Title: LEAD SOLDER INDICATOR AND METHOD



(57) Abstract: A solder system (14) includes a lead (Pb) indicator and a solder flux. A method for forming a semiconductor device includes providing a carrier (52), applying the solder system to the carrier (54), coupling the terminal to the carrier via the solder system (56), melting the solder system to attach the terminal to the carrier and form a completed semiconductor device (58), and determining if the completed semiconductor device has a different predetermined property from the solder system (60).



Published:

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